



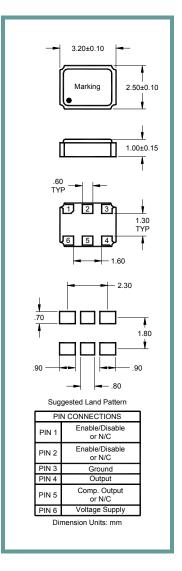
#### **Product Features**

Small Surface Mount Package Fast Sample Delivery Fast Sample Delivery Pb Free/ RoHS Compliant Leadfree Processing

### **Applications**

xDSL Broadcast Video Wireless Base Stations Sonet /SDH WiMAX/WLAN Server and Storage Ethernet/LAN/WAN
Optical modules
Clock and data recovery
FPGA/ASIC
Backplanes
GPON

Frequency			
LVCMOS	10.000MHz to 250.000MHz		
LVPECL	10.000MHz to 1500.000MHz		
LVDS	10.000MHz to 1500.000MHz		
Output Level			
LVCMOS	Logic "0" = 10% of Vcc min, Logic "1" = 90% of Vcc max		
LVPECL	Logic "0"= Vcc-1.62V max., Logic "1" = 1.02 V min		
LVDS	VOD=(Diff. Output) 350mV Typ.		
Duty Cycle			
LVCMOS	50% ±5% @ 50% of Vcc		
LVPECL	50% ±5% @ 50%*		
LVDS	50% ±5% @ 50%*		
Rise / Fall Time			
LVCMOS	2.0 ns max. (10% to 90%)*		
LVPECL	0.8 ns max. (20% to 80%)*		
LVDS	0.8 ns max. (20% to 80%)*		
Output Load			
LVCMOS	15pF		
LVPECL	50 Ω to Vcc - 2.0 VDC		
LVDS	RL=100 Ω/CL= 5pF		
Frequency Stability	See Table Below		
Supply Voltage (Vcc)	+3.30 VDC ± 5%, +2.50 VDC ± 5%		
Aging	±3.0 ppm max per year		
Current	HCMOS = 45 mA max		
	LVPECL = 90 mA max		
	LVDS = 35 mA max		
Phase Jitter (RMS)	0.5 ps typical		
At (12kHz to 20MHz)			
Operating Temp. Range	See Table Below		
Storage Temp. Range	-40° C to +85° C		



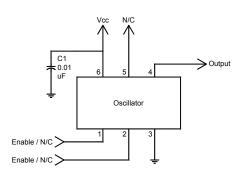
Part Number Guide Sam			ple Part Number: ISM75-31A9H2-15		-31A9H2-155.520		
Package	Input Voltage	Operating Temperature	Stability (in ppm)	Output	Enable / Disable	Complimentary Ouput (Pin 5) **	Frequency
ISM75	3 = 3.3V	1 = 0° C to +70° C	F = ±20	3 = LVCMOS	H = Enable (Pin 1)	1 = N.C.	-155.520 MHz
	6 = 2.5V	2 = -40° C to +85° C	A = ±25	8 = LVDS	K = Enable (Pin 2)	2 = Output	
		3 = -20° C to +70° C	B = ±50	9 = LVPECL			

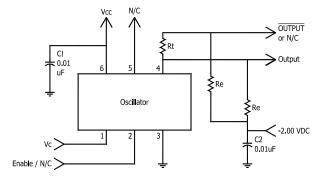
NOTE: A 0.01  $\mu$ F bypass capacitor is recommended between  $V_{DD}$  (pin 6) and GND (pin 3) to minimize power supply noise. \* Measured as percent of waveform. \*\* Available on LVDS and LVPECL ouput only.





# **Typical Application:**

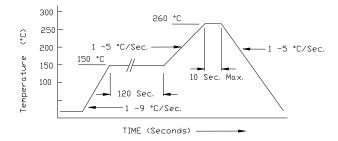




- Notes;

  1. LVPECL Load = Use Re and -2.0 VDC Source,
- LVDS Load = Omit Re and use Rt.

## Pb Free Solder Reflow Profile:



\*Units are backward compatible with 240C reflow processes

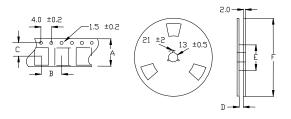
## Package Information:

MSL = N.A. (package does not contain plastic, storage life is unlimited under normal room conditions). Termination = e4 (Au over Ni over W base metallization).





# **Tape and Reel Information:**



Quantity per Reel	1000
Α	16 +/3
В	8 +/2
С	7.5 +/2
D	17.5 +/-1
E	50 / 60 / 80
F	180 / 250

# **Environmental Specifications**

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

## Marking

Line 1: ILSI and Date Code (YWW) Line 2: Frequency

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